

## WNM4153

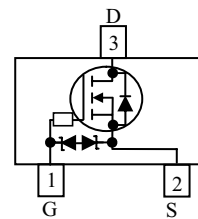
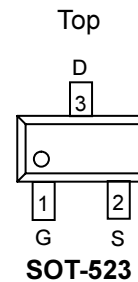
N-Channel, 20V, 0.88A, Small Signal MOSFET

[Http://www.willsemi.com](http://www.willsemi.com)

$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )
20	0.220 @ $V_{GS}=4.5V$
	0.260 @ $V_{GS}=2.5V$
	0.320 @ $V_{GS}=1.8V$

### Descriptions

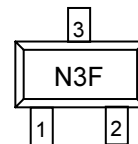
The WNM4153 is the N-Channel enhancement MOS Field Effect Transistor, uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use in DC-DC conversion applications. Standard Product WNM4153 is Pb-free.



### Pin Configuration

### Features

- Trench N-Channel
- Supper high density cell design for extremely low  $R_{ds(on)}$
- Exceptional ON resistance and maximum DC current capability
- Small package design with SOT-523



N3 = Device Code

F = Month

### Marking

### Applications

- Driver: Relays, Solenoids, Lamps, Hammers
- Power supply converters circuit
- Load/Power Switching for potable device

### Order Information

Device	Package	Shipping
WNM4153-3/TR	SOT-523	3000/Tape&Reel

**Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Parameter		Symbol	10 S	Steady State	Unit
Drain-Source Voltage		$V_{DS}$	+20		V
Gate-Source Voltage		$V_{GS}$	$\pm 6$		
Continuous Drain Current <sup>a</sup>	$T_A=25^\circ\text{C}$	$I_D$	0.88	0.80	A
	$T_A=70^\circ\text{C}$		0.71	0.64	
Maximum Power Dissipation <sup>a</sup>	$T_A=25^\circ\text{C}$	$P_D$	0.37	0.30	W
	$T_A=70^\circ\text{C}$		0.23	0.19	
Continuous Drain Current <sup>b</sup>	$T_A=25^\circ\text{C}$	$I_D$	0.76	0.69	A
	$T_A=70^\circ\text{C}$		0.60	0.55	
Maximum Power Dissipation <sup>b</sup>	$T_A=25^\circ\text{C}$	$P_D$	0.27	0.22	W
	$T_A=70^\circ\text{C}$		0.17	0.14	
Pulsed Drain Current <sup>c</sup>		$I_{DM}$	1.4		A
Operating Junction Temperature		$T_J$	150		$^\circ\text{C}$
Lead Temperature		$T_L$	260		$^\circ\text{C}$
Storage Temperature Range		$T_{stg}$	-55 to 150		$^\circ\text{C}$

**Thermal Resistance Ratings ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$t \leq 10$ s	$R_{\theta JA}$	285	335	$^\circ\text{C/W}$
	Steady State		340	405	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	$t \leq 10$ s	$R_{\theta JA}$	385	450	
	Steady State		455	545	
Junction-to-Case Thermal Resistance		$R_{\theta JC}$	260	300	

a Surface mounted on FR4 Board using 1 square inch pad size, 1oz copper

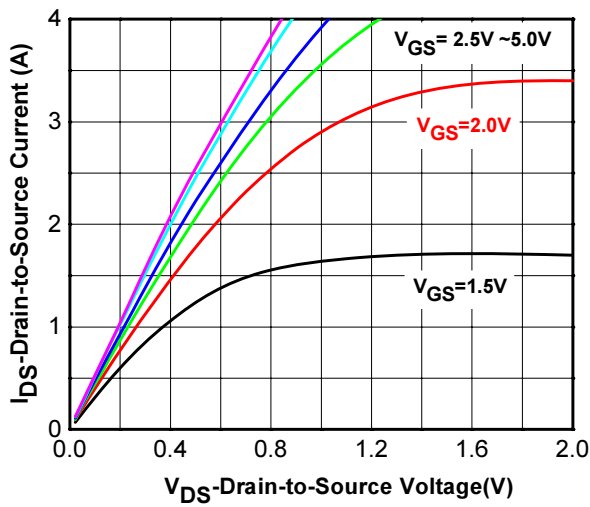
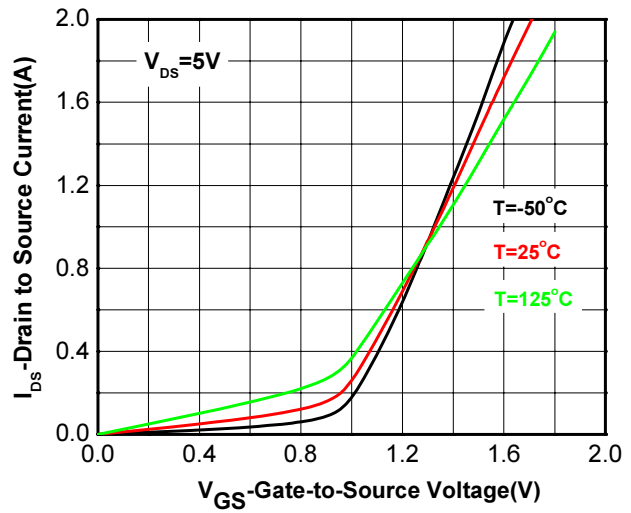
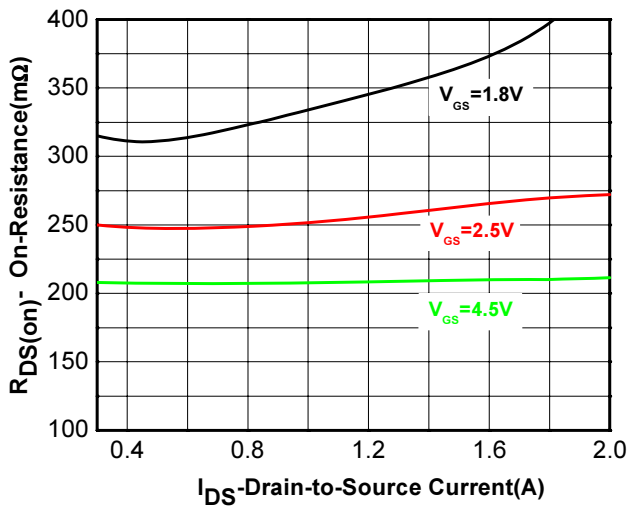
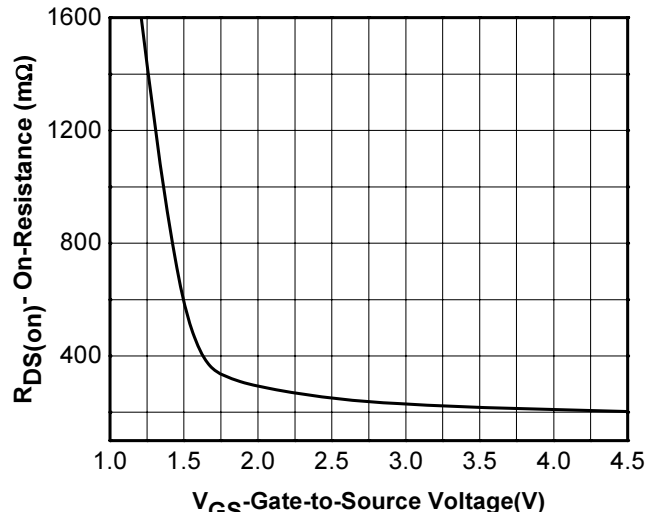
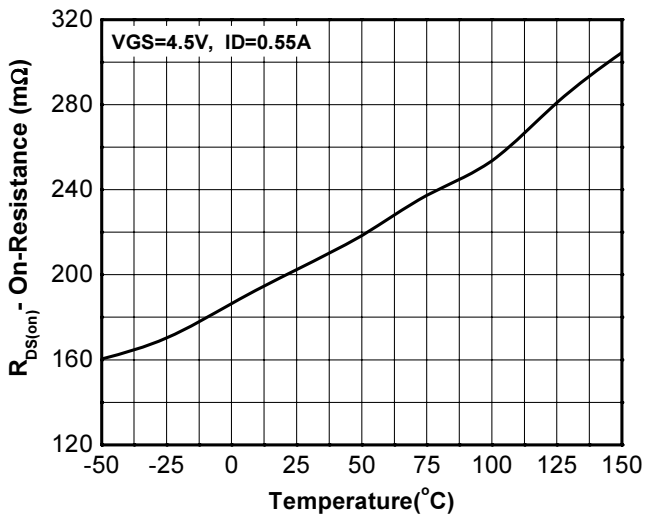
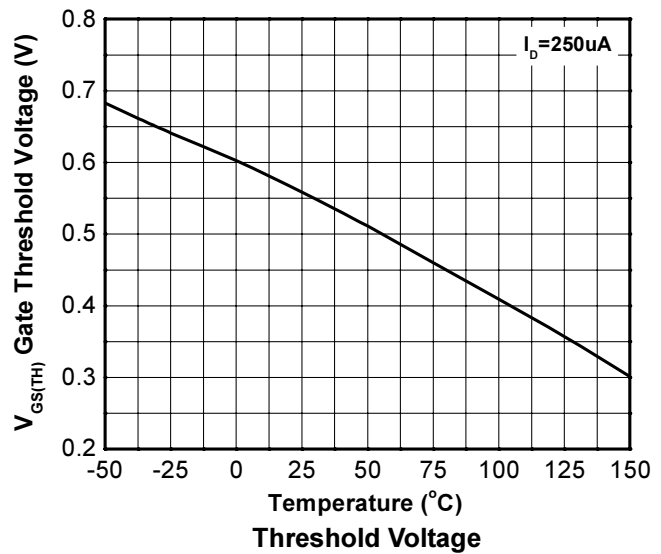
b Surface mounted on FR4 board using minimum pad size, 1oz copper

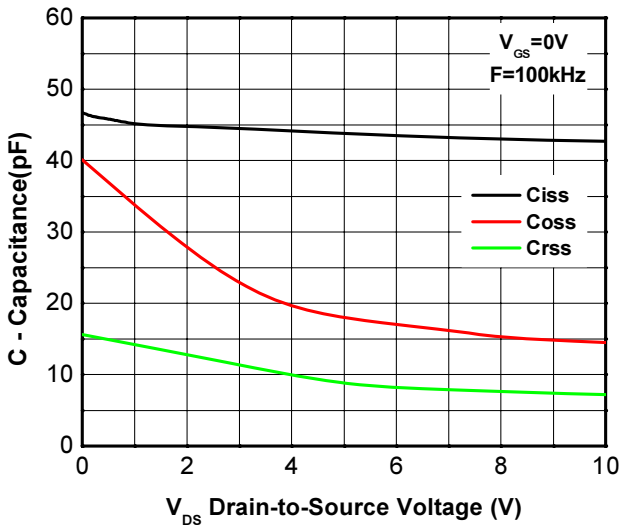
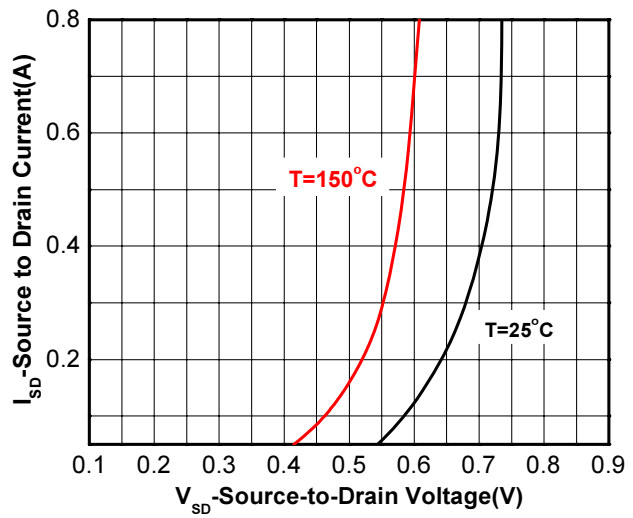
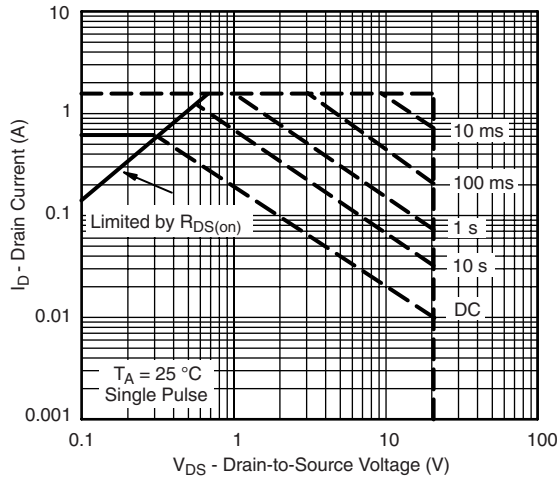
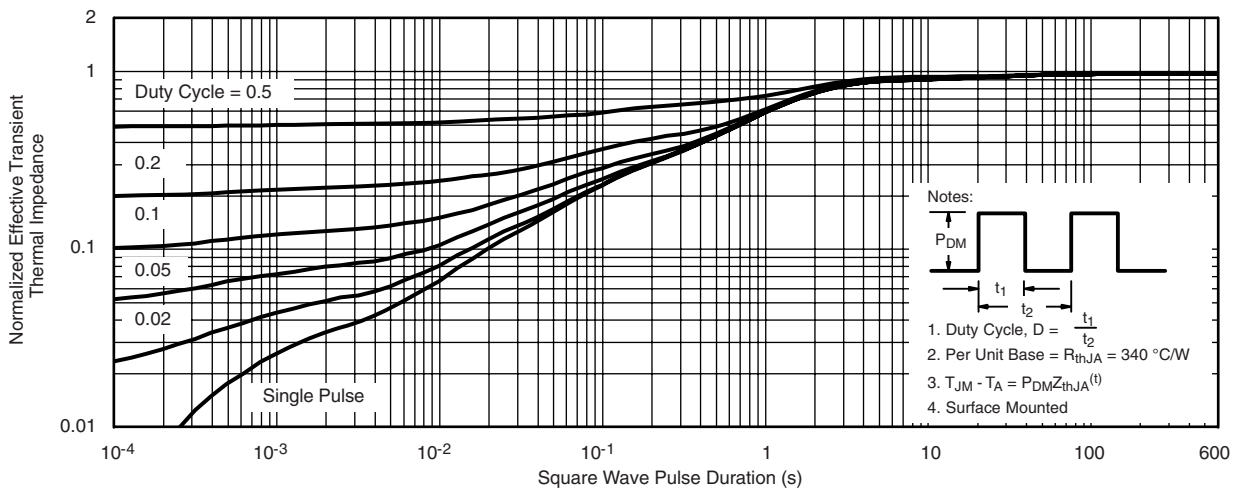
c Repetitive rating, pulse width limited by junction temperature,  $t_p=10\mu\text{s}$ , Duty Cycle=1%

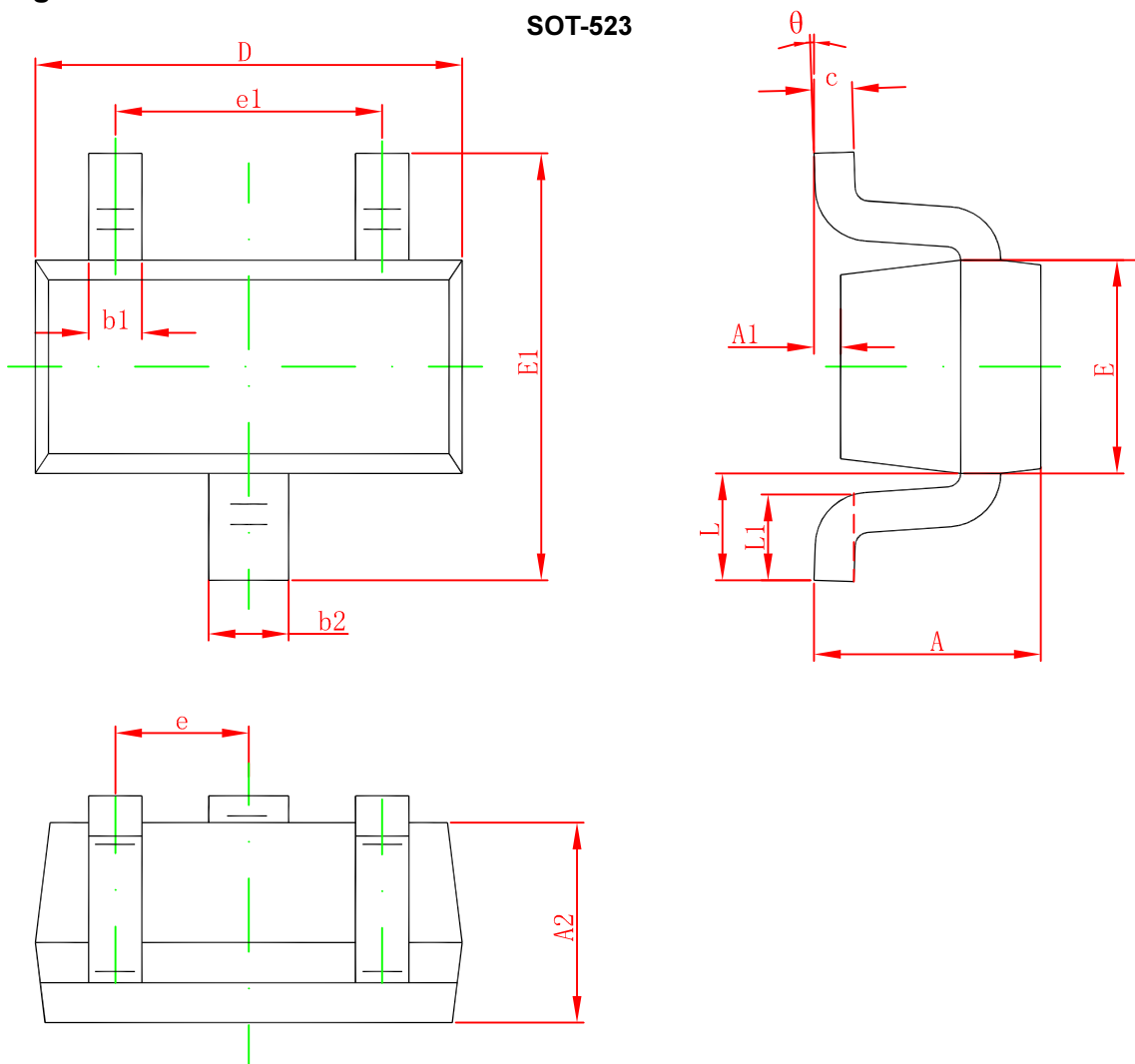
d Repetitive rating, pulse width limited by junction temperature  $T_J=150^\circ\text{C}$ .

**Electronics Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Test Condition	Min	Typ.	Max	Unit
<b>Off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	20			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V			1	uA
I <sub>GSS</sub>	Gate –Source leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±5V			±5	uA
<b>ON Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250uA	0.45	0.55	1.0	V
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.55A		220	310	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =0.45A		260	360	mΩ
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =0.35A		320	460	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =0.4A		1.0		S
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=100kHz		68		pF
C <sub>oss</sub>	Output Capacitance			9.0		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			7.5		pF
Q <sub>G(TOT)</sub>	Total Gate Charge	V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.55A		1.15		nC
Q <sub>G(TH)</sub>	Threshold gate charge			0.06		nC
Q <sub>GS</sub>	Gate-Source Charge			0.15		nC
Q <sub>GD</sub>	Gate-Drain Charge			0.23		nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =10V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.55A, R <sub>G</sub> =6Ω		22		ns
t <sub>r</sub>	Turn-On Rise Time			80		ns
t <sub>d(off)</sub>	Turn-Off Delay Time			700		ns
t <sub>f</sub>	Turn-Off Fall Time			380		ns
<b>Body Diode Characteristics</b>						
V <sub>SD</sub>	Forward Diode Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =0.35A	0.5	0.7	1.5	V

**Typical Performance Graph**

**Output Characteristics**

**Transfer Characteristics**

**On Resistance vs. Drain Current**

**On Resistance vs.  $V_{GS}$  vs. Temperature**

**On Resistance vs. Junction Temperature**

**Threshold Voltage**


**Capacitance**

**Body Diode Characteristics**

**Safe Operation Area, Junction-to-Ambient**

**Transient thermal response (Junction-to-Ambient)**

**Package Outline Dimensions**
**SOT-523**


Symbol	Dimension in Millimeters	
	Min.	Max.
A	0.700	0.900
A1	0.000	0.100
A2	0.700	0.800
b1	0.150	0.250
b2	0.250	0.350
c	0.100	0.200
D	1.500	1.700
E	0.700	0.900
E1	1.450	1.750
e	0.500 Typ.	
e1	0.900	1.100
L	0.400 Ref.	
L1	0.260	0.460
θ	0°	8°